

Weidmüller Interface GmbH & Co. KG

Klingenbergstraße 26 D-32758 Detmold Germany

www.weidmueller.com



















The new benchmark for component density: the virtual 0.875mm pitch - for 1mm² I/O connections

The only 4-row double level male connectors for standard IP20 sensor interfaces with 3.5 pitch

The S2L in a double pack - a standard has surpassed itself:

- Each 3.5mm wide, 4 I/O contacts for 1mm² connection cross-section
- Force-fit enclosure geometry guarantees maximum stability
- Solder flange eliminates the need for a screw fastening

Less is more - basic advantages for your applications:

- 75% space savings on the circuit board
- Solder flange reduces process costs
- · Less mechanical load on the soldering points
- More space for displays in the front panel, for example

A "small" contribution to greater competitiveness: additional features in the same installation space or a more compact device with the same range of functions.

General ordering data

Version	PCB plug-in connector, male header, closed side, THT/THR solder connection, 3.50 mm, Number of poles: 24, Solder pin length (I): 3.2 mm, tinned, black, Box	
Order No.	<u>1065340000</u>	
Туре	S2LD-THR 3.50/24/90G 3.2SN BK BX	
GTIN (EAN)	4032248818518	
Qty.	20 pc(s).	
Product data	IEC: 200 V / 10 A UL: 150 V / 7 A	
Packaging	Вох	



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Technical data

Dimensions and weights

Depth	24.4 mm	Depth (inches)	0.961 inch
Height	35 mm	Height (inches)	1.378 inch
Height of lowest version	31.8 mm	Net weight	12.6 g

System specifications

Product family	OMNIMATE Signal - series	Type of connection	
	B2L/S2L 3.50 - 2-row		Board connection
Mounting onto the PCB	THT/THR solder	Pitch in mm (P)	
	connection		3.5 mm
Pitch in inches (P)	0.138 inch	Number of poles	24
Number of solder pins per pole	1	Solder pin length (I)	3.2 mm
Solder pin dimensions	d = 1.0 mm, Octagonal	Solder eyelet hole diameter (D)	1.3 mm
Solder eyelet hole diameter tolerance (D)+ 0,1 mm		Outside diameter of solder pad	2.1 mm
Template aperture diameter	1.9 mm	L1 in mm	17.5 mm
L1 in inches	1.516 inch	Number of rows	2
Pin series quantity		Touch-safe protection acc. to DIN VDE	Safe from finger touch,
	4	57 106	plugged
Touch-safe protection acc. to DIN VDE	IP20 plugged/ IP10	Can be coded	
0470	unplugged		Yes
Plugging force/pole, max.	3 N		

Material data

Insulating material	LCP GF	Colour	black
Colour chart (similar)	RAL 9011	Insulating material group	IIIb
Comparative Tracking Index (CTI)	≥ 175	Moisture Level (MSL)	1
UL 94 flammability rating	V-0	Contact material	Copper alloy
Contact surface		Layer structure of solder connection	23 µm Ni / 57 µm Sn
	tinned		glossy
Layer structure of plug contact	25 µm Sn / 13 µm Ni	Storage temperature, min.	-40 °C
Storage temperature, max.	70 °C	Operating temperature, min.	-50 °C
Operating temperature, max.	100 °C	Temperature range, installation, min.	-30 °C
Temperature range, installation, max.	100 °C		

Rated data acc. to IEC

tested acc. to standard	IEC 60664-1, IEC 61984	Rated current, min. number of poles (Tu=20°C)	10 A
Rated current, max. number of poles (Tu=20°C)	10 A	Rated current, min. number of poles (Tu=40°C)	9 A
Rated current, max. number of poles (Tu=40°C)	8.5 A	Rated voltage for surge voltage class / pollution degree II/2	200 V
Rated voltage for surge voltage class / pollution degree III/2	160 V	Rated voltage for surge voltage class / pollution degree III/3	100 V
Rated impulse voltage for surge voltage class/ pollution degree II/2 2.5 kV		Rated impulse voltage for surge voltage class/ pollution degree III/2	2.5 kV
Rated impulse voltage for surge voltage class/ contamination degree III/3	1.5 kV		



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Rated data acc. to CSA

Institute (CSA)	42	Certificate No. (CSA)	
			200039-1488444
Rated voltage (Use group B / CSA)	50 V	Rated voltage (Use group C / CSA)	50 V
Rated voltage (Use group D / CSA)	150 V	Rated current (Use group B / CSA)	5 A
Rated current (Use group C / CSA)	9.5 A	Rated current (Use group D / CSA)	9.5 A
Reference to approval values	Specifications are maximum values, details - see approval certificate.		
Packing			
Packaging	Box	VPE length	142 mm
VPE width	107 mm	VPE height	41 mm
Classifications		3	
ETIM 6.0	EC002637	ETIM 7.0	EC002637
ETIM 8.0	EC002637	ECLASS 9.0	27-44-04-02
ECLASS 9.1	27-44-04-02	ECLASS 10.0	27-44-04-02
ECLASS 11.0	27-46-02-01	ECLASS 12.0	27-46-02-01
Important note			
IDO (''	O (); TI 1 1		
IPC conformity	Conformity: The products are developed, manufactured and delivered according international recognized standards and norms and comply with the assured properties in the data sheet resp. fulfill decorative properties in accordance with IPC-A-610 "Class 2". Further claims on the products can be evaluated on request.		et resp. fulfill decorative propertie
Notes	Additional variants on request		
	Gold-plated contact surfaces on request		
	Spacing between rows: see hole layout		
	Rated current related to rated cross-section & min. No. of poles.		
	• P on drawing = pitch		
	· · · · · · · · · · · · · · · · · · ·	omponent itself. Clearance and creepage dista with the relevant application standards.	ances to other components are to

Approvals

ROHS

Conform

UL Website

E60693

Creation date September 15, 2022 11:07:21 PM CEST

UL File Number Search

Certificate No. (cURus)



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Technical data

Downloads

Approval/Certificate/Document of	
Conformity	Declaration of the Manufacturer
Engineering Data	CAD data – STEP
Catalogues	Catalogues in PDF-format
Brochures	FL DRIVES EN
	MB SMT EN
	FL DRIVES DE
	MB DEVICE MANUF. EN
	FL BUILDING SAFETY EN
	FL APPL LED LIGHTING EN
	FL INDUSTR.CONTROLS EN
	FL MACHINE SAFETY EN
	FL HEATING ELECTR EN
	FL APPL_INVERTER EN
	FL_BASE_STATION_EN
	<u>FL ELEVATOR EN</u>
	FL POWER SUPPLY EN
	FL 72H SAMPLE SER EN
	PO OMNIMATE EN
White paper surface mount technology	Download Whitepaper



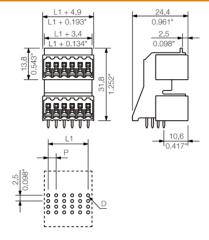
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Drawings

Dimensional drawing





Recommended wave solderding profiles

Weidmüller Interface GmbH & Co. KG

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Fon: +49 5231 14-0 Fax: +49 5231 14-292083 www.weidmueller.com

Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

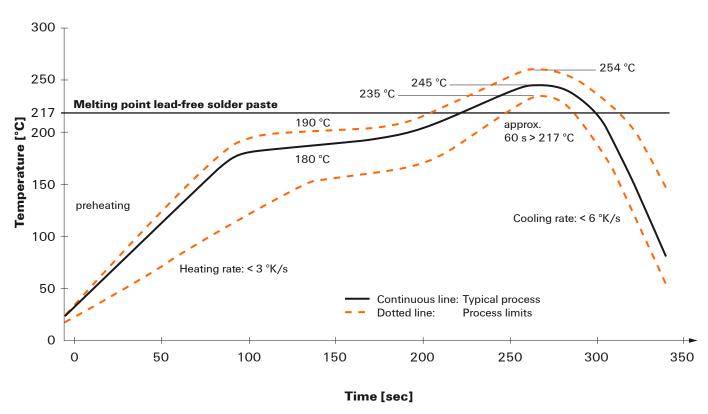


Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- · Time for pre heating
- Maximum temperature
- Time above melting point
- · Time for cooling
- · Maximum heating rate
- · Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3$ K/s. In parallel the solder paste is ,activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at \geq -6K/s solder is cured. Board and components cool down while avoiding cold cracks.